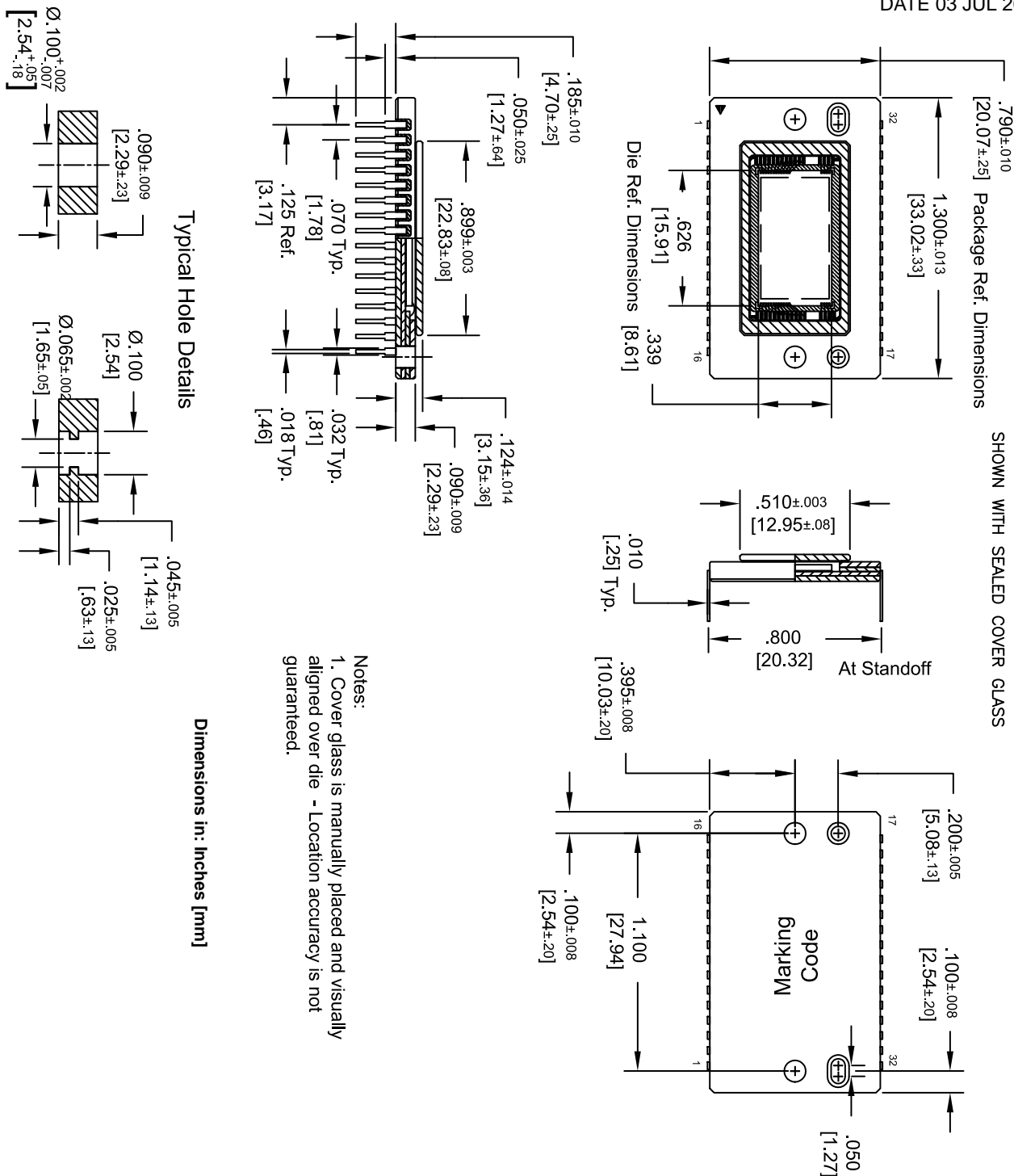


CERAMIC DIP 32, 33.02x20.07
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ISSUE O

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Notes:
1. Cover glass is manually placed and visually aligned over die - Location accuracy is not guaranteed.

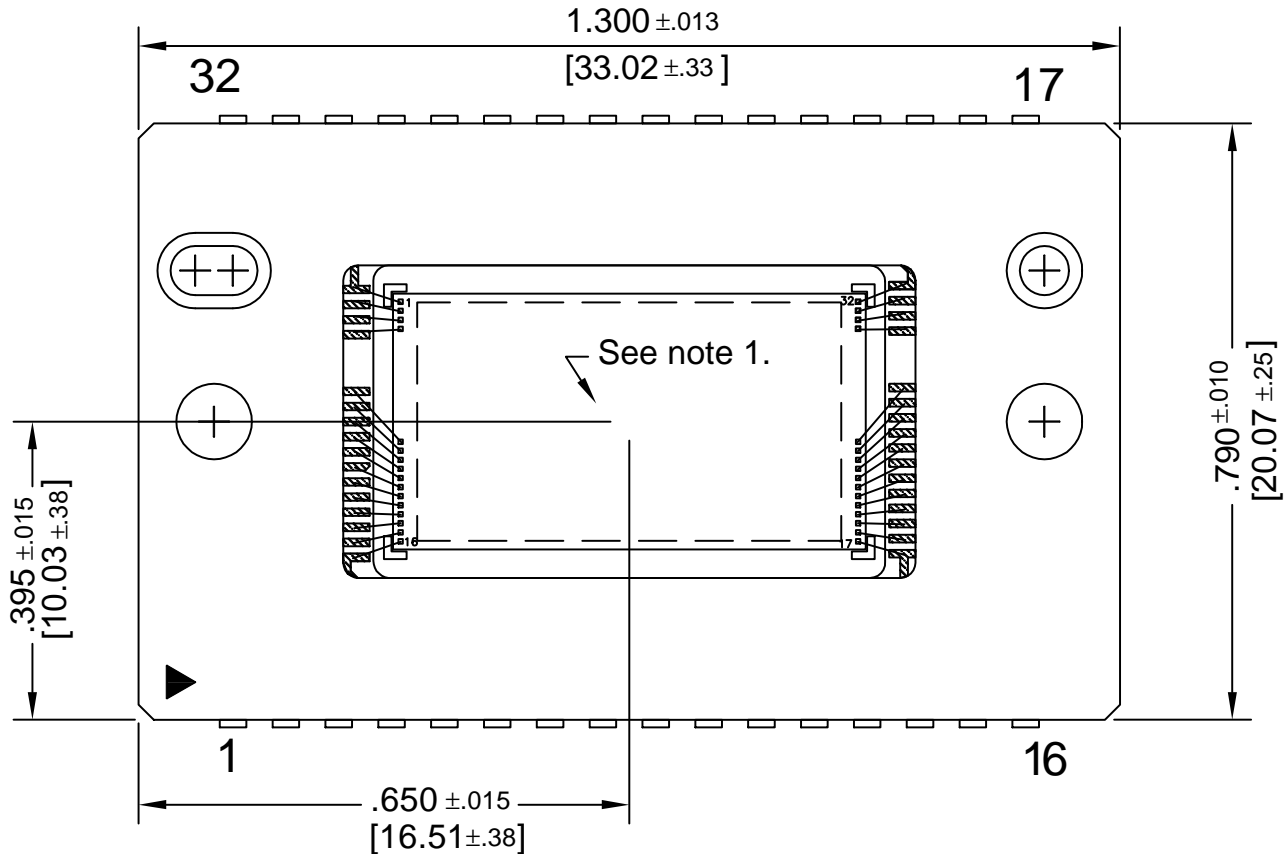
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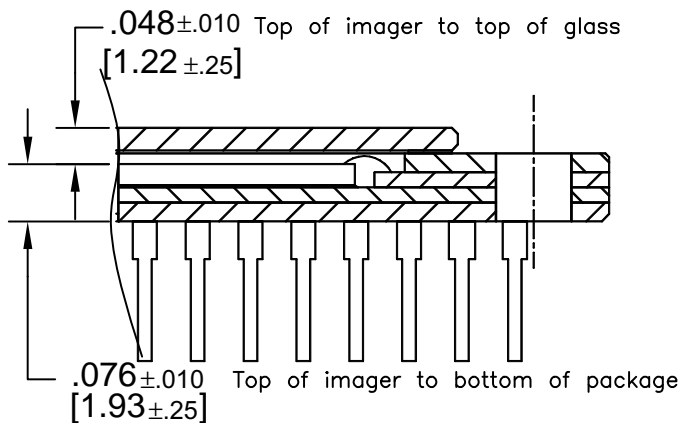
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SHOWN WITHOUT COVER GLASS



SHOWN WITH SEALED COVER GLASS



Notes:

1. Center of image is nominally coincident with the center of package.
2. Die is aligned within ± 2 degree of any package cavity edge.

Dimensions in: Inches [mm]

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